LINQBOND™ DA-8410

Silver Sintering Die Attach Paste

- High thermal conductivity
- Excellent adhesion on bare Cu substrate
- Pressureless sintering

LINQBOND™ DA-8410 is a silver sintering die attach paste with excellent adhesion on bare Cu substrates, as well as other metal plated substrates. Pressureless sintering is achieved at 250 °C, providing excellent adhesion and leaving no organic residues, resulting in high thermal conductivity and reliability.

LINQBOND™ DA-8410 is designed as a die attach material for applications requiring high thermal and electrical conductivity. Typically used for high thermal resistance assemblies such as LEDs, laser diodes, RF devices, automotive electronics, and power devices.

Cure Schedule (2-step cure)

- 1st step: 5 °C/min ramp to 80 °C and hold for 30 min
- 2nd step: 5 °C/min ramp from 80 °C to 250 °C and hold for 60 min
- Cool down: 5 to 10 °C/min cool down to room temperature

Uncured properties

Property	Value	Unit
Filler Content	89	%
Viscosity *at 25 °C (5 rpm)*	40000	cPs
Thixotropic Index *(0.5/5 rpm)*	5.9	–
Work Life *at 25 °C*	24	hours
Shelf Life *at –15 °C*	6	months

Cured properties*

Property	Value	Unit
Thermal Conductivity	250	$W/m \cdot K$
Volume Resistivity	5.5×10^{-6}	$\Omega \cdot cm$
Coefficient of Thermal Expansion (CTE)	18	ppm/°C
Shear Strength*		
Ag vs Ag at 25°C	20	MPa
Cu vs Cu at 25°C	15	MPa

** Above data was obtained based on our internal test methods and are intended for reference purpose only.*

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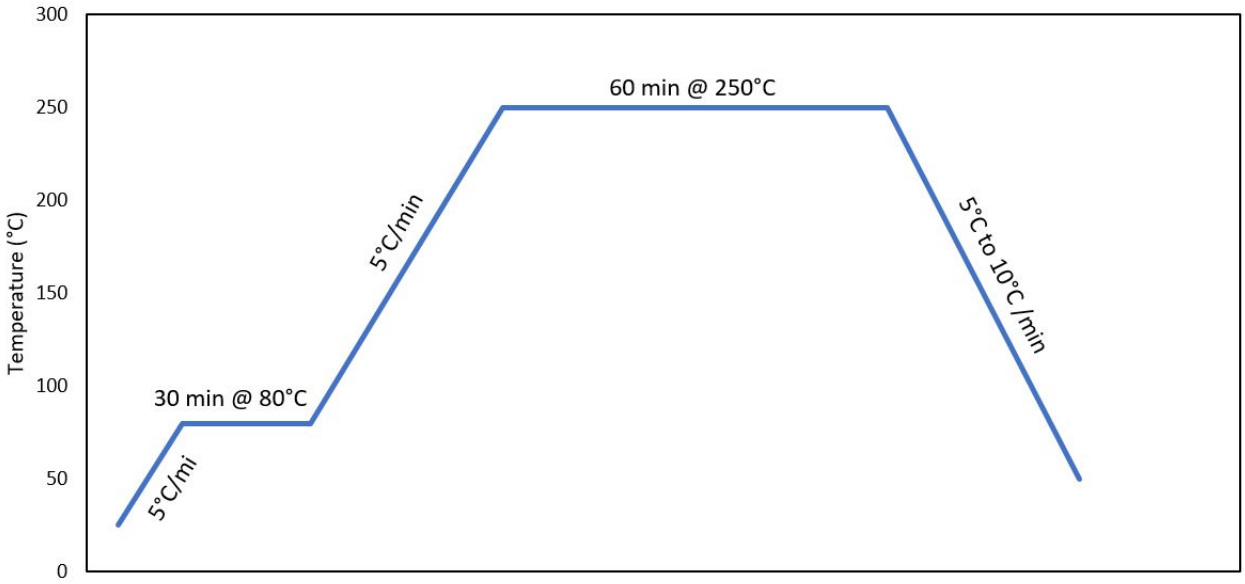
Two-Step Curing Conditions *(refer to the diagram below):*

- 1st step: 5 °C/min ramp to 80 °C and hold for 30 min
- 2nd step: 5 °C/min ramp from 80 °C to 250 °C and hold for 60 min
- Cool down: 5 to 10 °C/min cool down to room temperature



Precautions for Use

1. Allow the container to reach room temperature before use. Syringe should be placed vertically while thawing. Thaw process for 10 cc syringe takes 1 hour.
2. The adhesive cannot be refrozen once exposed to room temperature.
3. To ensure uniform and stable viscosity, syringe can be placed in planetary mixer for 2 min at 800 rpm.
4. Please note that the provided information is based on available data and typical conditions. For specific applications and detailed test results, refer to the actual test data and conduct appropriate certifications.

Storage and Handling

Store and transport in temperatures ≤ −15 °C. Keep away from fire and heat sources.

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